Special Issue

Tactile Sensing Technology and Systems

Message from the Guest Editor

Tactile sensors acquire tactile information through physical touch; measurands are, for example, temperature, vibration, softness, texture, shape, composition and shear and normal forces. Electronic/artificial skin comprises embedded electronic systems which integrate tactile sensing arrays, signal acquisition, data processing and decoding, and can transmit collated information. Such electronic/artificial skin will become one of the main sensing essentials in prosthetics, bionics, robotics, virtual reality, haptic devices, IoT, etc. In this Special Issue, we focus on both insights and advancements in tactile sensing with the goal of bridging different research areas, e.g., material science, electronics, robotics, neuroscience, mechanics, sensors, MEMS/NEMS, addictive and 3D manufacturing, bio and neuro-engineering. We would like to receive commentaries, perspectives and insightful reviews on related topics as well as technological breakthroughs of original works, civil and industrial applications in both short communications and full papers.

Guest Editor

Prof. Dr. Maurizio Valle

Department of Electrical, Electronic, Telecommunications Engineering and Naval Architecture, University of Genova, Via Opera Pia 11A, I16145 Genova, Italy

Deadline for manuscript submissions

closed (31 August 2019)

Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed

mdpi.com/si/18680

Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

mdpi.com/journal/micromachines

Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed

mdpi.com/journal/micromachines

About the Journal

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Editor-in-Chief

Prof. Dr. Ai-Qun Liu
1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

Author Benefits

High Visibility:

indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

Journal Rank:

JCR - Q2 (Instruments and Instrumentation) / CiteScore - Q1 (Mechanical Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 17.2 days after submission; acceptance to publication is undertaken in 1.9 days (median values for papers published in this journal in the first half of 2025).

MDPI